



PRODUCT SELECTION GUIDE



SoM











Development Kit









Embedded PC








Accessories

	NXP Model Options 				TI Model Options		
Image							
Model	FET-MX9352-C	FETMX8MP-C	FETMX8MM-C	FETMX6GULL-C	FET6254-C	FET6232-C	FET6231-C
Processor	NXP i.MX9352	NXP i.MX8M Plus	NXP i.MX8M Mini	NXP i.MX6GULL	TI AM62x	TI AM62x	TI AM62x
Architecture	Cortex-A55+M33	Cortex-A53+M7	Cortex-A53+M4	Cortex-A7	Cortex-A53 + M4F	Cortex-A53 + M4F	Cortex-A53 + M4F
Core	2×A55+1×M33	4×A53 + 1×M7	4×A53+1×M4	1	4×A53 + 1×M4F	2×A53 + 1×M4F	1×A53 + 1×M4F
Frequency	1.5GHz+250MHz	1.6GHz + 800MHz	1.8GHz/1.6GHz+400MHz	800MHz	1.4GHz + 400MHz	1.4GHz + 400MHz	1.0GHz + 400MHz
RAM	1GB LPDDR4	1/2/4GB LPDDR4	2GB DDR4	512MB	1/2GB DDR4	2GB DDR4	1GB DDR4
ROM	8GB eMMC	8/16GB eMMC	8GB eMMC	8GB eMMC	8GB eMMC	8GB eMMC	8GB eMMC
GPU	-	GC7000UL (3D) GC520L (2D) OpenGL/OpenCL/Vulkan	GCNanoUltra (3D) GC320 (2D) OpenGL/OpenVG	2D PXP	AXE1-16M@500MHz OpenGL/Vulkan	-	-
NPU	0.5 TOPS	2.3 TOPS	-	-	-	-	-
VPU-Decode	-	1080p60 VP8/VP9/H.264/H.265	1080p60 VP8/VP9/H.264/H.265	-	-	-	-
VPU-Encode	-	1080p60 H.264/H.265	1080p60 H.264/VP8	-	-	-	-
OS	Linux 5.15/6.1	Linux 5.4	Linux 4.14	Linux 4.1	Linux 5.10/6.1	Linux 5.10/6.1	Linux 5.10/6.1
	-	Android 11	Android 9.0	-	-	-	-
	-	-	-	-	-	-	-
Operating Temperature	-40°C~+85°C	-40°C~+85°C	0°C~+70°C/-40°C~+85°C	-40°C~+85°C	-40°C~+85°C	-40°C~+85°C	-40°C~+85°C
Dimensions	33mm×48mm	36mm×62mm	36mm×56mm	29mm×40mm	38mm×60mm	38mm×60mm	38mm×60mm
Connection	B to B	B to B	B to B	B to B	B to B	B to B	B to B
Input voltage	5V	5V	5V	3.3V	5V	5V	5V
Interface							
Display	RGB	1366×768	converted from MIPI-DSI	converted from MIPI-DSI	1366×768	1920×1200	1920×1200
	LVDS	1366×768	1920×1200	converted from MIPI-DSI	available through conversion	1920×1200	1920×1200
	HDMI	-	3840×2160	converted from MIPI-DSI	available through conversion	available through conversion	available through conversion
	MIPI-DSI	1920×1200	2560×1440	1920×1200	-	-	-
	eDP	-	-	-	-	-	-
Ethernet	2×1Gbps MAC, RGMII 1 supports TSN	2×1Gbps MAC, RGMII 1 supports TSN	1×1Gbps MAC, RGMII	2×100Mbps MAC, RMII	2×1Gbps MAC RGMII (support TSN)	2×1Gbps MAC RGMII (support TSN)	2×1Gbps MAC RGMII (support TSN)
UART	8	4	4	≤8	≤9	≤9	≤9
CAN	2×CAN-FD	2×CAN-FD	-	≤2	≤3×CAN-FD	≤3×CAN-FD	≤3×CAN-FD
Audio	3×SAI	≤6×SAI	≤5×SAI	≤3×SAI	≤3	≤3	≤3
IIC	8×I2C, 2×I3C	5	4	≤4	≤6	≤6	≤6
SPI	8	≤3	3×eCSPI, 1×FlexSPI	≤4	≤5×SPI, ≤1×OSPI	≤5×SPI, ≤1×OSPI	≤5×SPI, ≤1×OSPI
USB	2×USB 2.0	2×USB 3.0	2×USB 2.0	2×USB 2.0	2×USB 2.0	2×USB 2.0	2×USB 2.0
SD/SDIO	2	≤2	≤2	≤2	≤2×SDIO 3.0	≤2×SDIO 3.0	≤2×SDIO 3.0
PCIe	-	1×PCIe 3.0 x1	1×PCIe 2.0 x1	-	-	-	-
SATA	-	-	-	-	-	-	-
ADC	4	-	-	≤10	-	-	-
Camera	1×MIPI CSI	2×MIPI-CSI 4-lane	1×MIPI-CSI 4-lane	≤1×DVP	1×MIPI-CSI	1×MIPI-CSI	1×MIPI-CSI
Parallel Bus	-	-	-	-	16 bit data, 22 bit address 4 chip select, 133MHz clock	16 bit data, 22 bit address 4 chip select, 133MHz clock	16 bit data, 22 bit address 4 chip select, 133MHz clock







Note: 1. The parameters mentioned above indicate the highest capabilities that the native CPU can support. Some pins may have multiplexing abilities, and the specific situation depends on the software configuration. 2. In case some interfaces are not enough, they can be obtained through other interfaces like USB to UART, SPI to CAN, etc.

	Allwinner Model Options				Rockchip Model Options			
Image								
Model	FETS27N-C	FETT507-C	FETA40i/T3-C	FET113i-S	FET3588/3588J-C		FET3568/3568J-C	
Processor	Allwinner T527	Allwinner T507	Allwinner A40i/T3	Allwinner T113-i	RK3588	RK3588J	RK3568	RK3568J
Architecture	Cortex-A55	Cortex-A53	Cortex-A7	2×Cortex-A7+HiFi4 DSP +XuanTie C906 RISC-V	Cortex-A76+A55		Cortex-A55	
Core	8	4	4	2	4×A76+4×A55		4	
Frequency	1.8GHz	1.5GHz	1.2GHz	1.2GHz	2.4GHz+ 1.8GHz	1.6GHz+ 1.3GHz	2.0GHz	1.8GHz
RAM	2/4GB LPDDR4	1/ 2GB DDR3	1/ 2GB DDR3	512/256MB DDR3	4/8GB LPDDR4		1/2/4/8GB DDR4	
ROM	16/32GB eMMC	8GB eMMC	8GB eMMC	8GB eMMC 256MBNand Flash	32/64GB eMMC		8/16/32GB eMMC	
GPU	ARM G57 MC1	G31 MP2 OpenGL ES/OpenCL/ Vulkan	Mali400 MP2 OpenGL ES/OpenVG	-	Mail-G610 MP4 OpenGL ES 1.1/2.0/3.2 OpenCL 2.2/ Vulkan 1.2		Mali-G52-2EE OpenGL ES/Vulkan OpenCL	
NPU	2TOPS	-	-	-	6 TOPS		1TOPS	
VPU-Decode	H.265, 4K@60fps H.264, 4K@30fps	4Kp60/4Kp30/1080p60 H.265/H.264/VP8	1080p60 VP8/H.264	H.265/H.264 4K@30fps	8Kp60 / 8Kp30 /4Kp60 H.265 / H.264 / VP9/AV1		4Kp60 / 1080p60 H.264/H.265/VP9 / VP8	
VPU-Encode	H.264, 4K@25fps	4Kp60 H.264/VP8	1080p45 H.264	JPEG/MJPEG 1080p@60fps	8Kp30 H.264/HEVC/H.264/AVC		1080p60 H.264/H.265	
OS	Linux5.15	Linux4.9	Linux3.10/5.10	Linux5.4	Linux5.10		Linux4.19/5.10,	
	-	Android10	Android7.1	-	Android12		Forlinx Desktop, Android11,	
	-	Forlinx Desktop18.04	Forlinx Desktop16.04	-	Forlinx Desktop20.04		Debian 11, AMP	
Operating Temperature	-40°C~+85°C	0°C~+70°C/ -40°C~+85°C	-25°C~ +85°C/ -40°C~+85°C	-40°C~+85°C	0°C~+80°C	-40°C~+85°C	0°C~+80°C	-40°C~+85°C
Dimensions	46mm×70mm	40mm×70mm	45mm×68mm	44mm×35mm	50mm×68mm		45mm×70mm	
Connection	B to B	B to B	B to B	Edge soldering	B to B		B to B	
Input voltage	5V	5V	5V	5V	12V		5V	
Interface								
Display	RGB	1920×1080	1920×1080	1920×1080	-		1280×800	
	LVDS	1280×720	1920×1080	1920×1080	DP (8K)		1280×800	
	HDMI	4K	4K	1920×1080	8K		4K	
	MIPI-DSI	4K	-	1920×1080	4K		2560×1440	
	eDP	4K	-	-	-		4K	
Ethernet	≤2 GMAC, RMII/RGMI	1×100Mbps MAC, RMII, 1×1Gbps MAC, RGMII	1×100Mbps MAC, MII 1×1Gbps MAC, RGMII	1Gbps MAC, RGMII/RMII	2×GMAC by RGMII/RMII 10/100/1000Mbps		2×1Gbps MAC, RGMII/QSGMII	
UART	≤10	≤6	≤8	≤5	≤10		≤10	
CAN	≤2	-	-	≤2	≤3×CAN		≤3×CAN2.0	
Audio	1	≤4	≤3	≤3×I2S/PCM	4×I2S, 2×SPDIF, 2×PDM		≤4	
IIC	≤8TWI, compatible with IIC	≤5	≤5	3	≤9		≤5	
SPI	≤4	≤2	≤4	1	≤5		≤4	
USB	2×USB 2.0+1×USB 3.1	4×USB 2.0	3×USB 2.0	2	2×USB 2.0+3×USB 3.1		2×USB 2.0+2×USB 3.0	
SD/SDIO	≤2	≤2	≤4	2	1×SDIO 3.0		≤2, SDIO 3.0	
PCIe	1×PCIe 2.1	-	-	-	≤3×PCIe 2.0+4×PCIe 3.0		2×PCIe3.0, 1×PCIe2.1	
SATA	-	-	1×SATA 2.0	-	≤3×SATA 3.0		≤3, SATA 3.0	
ADC	14×GPADC, 2×LRADC	4×GPADC, 1×LRADC	≤2	2×GPADC, 1×TPADC, 1×LRADC	≤8, 12bit		≤8, 10bit	
Camera	4×MIPI CSI, 1×Parallel CSI	1×4-lane MIPI-CSI, 1×DVP	2×DVP,4×TVIN	1, supports 8-bit digital camera interface	≤6×MIPI, 1×DVP		1×4-lane MIPI-CSI, 1×DVP	
Parallel Bus	-	-	-	-	-		-	








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	SemiDrive Model Options	StarFive Model Options	NXP i.MX6 Model Options			
Image						
Model	FET-D9360-C	FET7110-C	FETMX6GULL-S	FETMX6GUL-C	FETMX6Q/DL-C	
Processor	SemiDrive D9-Pro	StarFive JH7110	NXP i.MX6GULL	NXP i.MX6GUL	i.MX6Q	i.MX6DL
Architecture	Cortex-A55+Cortex-R5	RISC-V	Cortex-A7	Cortex-A7	Cortex-A9	
Core	6×A55+1×R5	4×RISC-V	1	1	4	2
Frequency	2.0GHz+800MHz	1.5GHz	800MHz	528MHz	1GHz	
RAM	2/4GB LPDDR4x	2/4GB LPDDR4	256/512MB DDR3	256/512MB DDR3	1/2GB DDR3	
ROM	16/32GB eMMC	32GB eMMC	256MB NAND, 8GB eMMC	256MB NAND, 8GB eMMC	8GB eMMC	
GPU	PowerVR 9XM 3D GPU 100GFLOPS	OpenCL 3.0 OpenGL ES 3.2 Vulkan 1.2	2D PXP	2D PXP	GC2000 (3D) GC320 (2D)	
NPU	0.4TOPS INT8	-	-	-	-	
VPU-Decode	H.264@4Kp30 H.265@4Kp30	4K@60fps/1080p@30fps H.264, H.265	-	-	1080p30 H.264/H.263/VP8/MPEG-4	
VPU-Encode	H.264@4Kp30	1080p@30fps H.265	-	-	1080p30 H.264/H.263/MPEG-4	
OS	Linux4.14	Linux5.15	Linux4.1	Linux4.1	Linux4.1	
	-	-	-	-	Android 4.4/6.0	
	-	-	-	-	-	
Operating Temperature	-40°C~+85°C	0°C~+80°C	0°C~+70°C/-40°C~+85°C	0°C~+70°C/-40°C~+85°C	0°C~+70°C/-40°C~+85°C	
Dimensions	44×65mm	60mm×38mm	35mm×44mm	40mm×50mm	40mm×70mm	
Connection	B to B	B to B	Edge soldering	B to B	B to B	
Input voltage	12V	5V	5V	5V	4.2V	
Interface						
Display	RGB	-	1920×1080	1366×768	1366×768	1920×1200
	LVDS	1920×1080	-	available through conversion	available through conversion	1920×1080
	HDMI	-	4K	available through conversion	available through conversion	1920×1080
	MIPI-DSI	2K	2K	-	-	1280×720
	eDP	-	-	-	-	-
Ethernet	2×1Gbps GMAC support TSN	2×1Gbps GMAC	2×100Mbps MAC, RMII	2×100Mbps MAC, RMII	1×1Gbps MAC, RGMII	
UART	≤16	≤6	≤8	≤8	5	
CAN	4×CAN-FD	2×CAN2.0B	≤2	≤2	≤2	
Audio	6×I2S	1×I2S/PCM, 2×SPDIF	≤3×SAI	≤3×SAI	≤3×SAI	
IIC	≤12	≤7	≤4	≤4	3	
SPI	8×SPI, 2×OSPI	≤7	≤4	4×SPI, 1×QSPI	5	
USB	2×USB 3.0	1×USB 2.0+1×USB 3.0	2×USB 2.0	2×USB 2.0	2×USB 2.0	
SD/SDIO	2	1	≤2	≤2	≤3	
PCIe	2×PCIe 3.0x1	2×PCIe 2.0x1	-	-	1×PCIe 2.0 x1	
SATA	-	-	-	-	1×SATA 2.0	-
ADC	4	-	≤10	≤10	-	
Camera	2×MIPI-CSI 4-lane	1×DVP, 1×MIPI	≤1×DVP	≤1×DVP	1×DVP, 1×MIPI-CSI	
Parallel Bus	-	-	-	-	27bit add, 32bit data	

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NXP Layerscape Model Options 					Renesas Model Options
Image					
Model	FET1012A-C	FET1028A-C	FET1043A-C	FET1046A-C	FET-G2LD-C
Processor	NXP LS1012A	NXP LS1028A	NXP LS1043A	NXP LS1046A	Renesas RZ/G2L
Architecture	Cortex-A53	Cortex-A72	Cortex-A53	Cortex-A72	Cortex-A55 + M33
Core	1	2	4	4	2×A55 + 1×M33
Frequency	≤1GHz	1.5GHz	≤1.6GHz	≤1.8GHz	1.2GHz + 200MHz
RAM	512MB DDR3L	2GB DDR4	2GB DDR4	2/4GB DDR4	1/2GB DDR4
ROM	8GB eMMC, 16MB NorFlash	8GB eMMC, 16MB NorFlash	8GB eMMC, 16MB NorFlash	8GB eMMC, 16MB NorFlash	QSPI NorFlash 16MB eMMC 8GB / 16GB
GPU	-	GC7000 (3D) OpenGL ES/OpenCL/ OpenVG/OpenCL	-	-	Mali-G31 OpenGL ES/Vulkan/ OpenCL
NPU	-	-	-	-	-
VPU-Decode	-	-	-	-	1920×1080p30 H.264
VPU-Encode	-	-	-	-	1920×1080p30 H.264
OS	-	-	-	-	Linux4.19
	OpenWrt v21.02	-	OpenWrt v21.02	OpenWrt v21.02	-
	Forlinx Desktop18.04	Forlinx Desktop18.04/20.04	Forlinx Desktop18.04	Forlinx Desktop18.04	-
Operating Temperature	-40°C~+80°C	-40°C~+85°C	-40°C~+80°C	-40°C~+75°C	-40°C~+85°C
Dimensions	40mm×45mm	42mm×65mm	55mm×84mm	55mm×84mm	38mm×60mm
Connection	B to B	B to B	COM-E	COM-E	B to B
Input voltage	4.2V	12V	12V	12V	5V
Interface					
Display	RGB	-	-	-	1280×800
	LVDS	-	available through conversion	-	available through conversion
	HDMI	-	DP (4Kp60)	-	available through conversion
	MIPI-DSI	-	-	-	1920×1080
	eDP	-	eDP 1.4 (4Kp60)	-	-
Ethernet	2, up to 2.5G bps	6, up to 2.5G bps, support TSN	7, supports 10/2.5/1Gbps combination	8, supports 10/2.5/1Gbps combination	2×1Gbps MAC, RGMII
UART	≤2	≤4	≤4	≤4	≤7
CAN	-	2×CAN-FD	-	-	≤2×CAN-FD
Audio	≤5×SAI	≤6×SAI	-	-	≤4
IIC	≤1	≤6	≤2	≤2	≤3
SPI	-	≤2	-	-	3×SPI, 1×QSPI
USB	1×USB 3.0	2×USB 3.0	3×USB 3.0	3×USB 3.0	2×USB 2.0
SD/SDIO	≤1	≤1×SD3.0	-	-	≤1
PCIe	≤1×PCIe 2.0 x1	≤2×PCIe 3.0 x2	≤3 PCIe2.0 (x1, x2, x4)	≤3 PCIe3.0 (x1, x2, x4)	-
SATA	≤1×SATA 3.0	≤1×SATA 3.0	≤1×SATA 3.0	≤1×SATA 3.0	-
ADC	-	-	-	-	≤8, 12bit
Camera	-	-	-	-	≤2×MIPI-CSI/DVP
Parallel Bus	-	-	-	-	-











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Embedded PC							
Image							
Model	FCU1101	FCU1103	FCU1104	FCU2201	FCU2303	FCU2401	FCU2601
Dimensions	105×100×33mm	147×103×42mm	150×110×45mm	135×100×70mm	232×155×53mm	236×152.8×53.3mm	190×140×45mm
Installation	Wall-mounting	Wall-mounting	Wall-mounting/ Din rail	Wall-mounting/ Din rail	Wall-mounting	Wall-mounting	Wall-mounting
Basic Parameters							
Processor	NXP i.MX6UL	NXP i.MX6UL	NXP i.MX6ULL	NXP LS1012A	NXP LS1046A	Allwinner A40i	RK3568J
Architecture	ARM Cortex-A7	ARM Cortex-A7	ARM Cortex-A7	ARM Cortex-A53	ARM Cortex-A72	ARM Cortex-A7	ARM Cortex-A55
Core	1	1	1	1	4	4	4
Frequency	528MHz	528MHz	800MHz	1GHz	1.8GHz	1.2GHz	1.8GHz
RAM	256MB	256/512MB	256/512MB DDR3	512MB	2GB	1/2GB	2/4GB
ROM	256MB / 1GB	256MB/1GB Nand Flash / 8GB eMMC	256MB Nand Flash / 8GB eMMC	8GB	8GB	8GB	16/32GB eMMC
GPU	-	-	-	-	-	-	Mali-G52-2EE, OpenCL OpenGL ES, Vulkan
AI	-	-	-	-	-	-	1TOPS
OS	Linux3.14/4.1	Linux3.14/4.1	Linux4.1	-	-	Linux3.10	Linux4.19
	-	-	-	ForlinxDesktop18.04	ForlinxDesktop18.04	-	ForlinxDesktop20.04
	-	-	-	OpenWRT	OpenWRT	-	-
Interface							
Display	-	LVDS (1280x800)	-	-	-	LVDS (1280×800) HDMI (1920×1080)	HDMI (4K)
Cellular	4G	4G	4G	4G / 5G	4G / 5G	4G	4G
Ethernet	1×10/100Mbps	1×10/100Mbps	2×10/100Mbps	2×10M/100M/1000Mbps	8×10M/100M/1000Mbps	1×10/100Mbps 1×10M/100M/1000Mbps	2×10/100Mbps 2×10M/100M/1000Mbps
WiFi	2.4GHz	2.4GHz	2.4GHz (alternative with 4G)	2.4GHz & 5GHz	2.4GHz & 5GHz	2.4GHz	supported
RS485	4	2	4 or 8	1 or 5	2 or 8	2	11×RS485
RS232	-	1	-	1, multiplexed with RS485	2 or 4	2	2×RS232/RS485
CAN	-	2	1	-	-	2	2, supports CAN2.0 B
USB	-	1×USB 2.0	-	1×USB 3.0	1×USB 3.0	2×USB 2.0	2×USB 2.0
DI	-	4	2	-	2	4	8, dry contact
DO	-	4	2	-	2	4	6, 30VDC/3A, contacts disconnected
Extended Storage	TF	TF	TF	TF	SSD	SATA	TF, mSATA
Voltage Input	DC 12V	DC 9V~15V	DC 9V~36V	DC 9V~36V	DC 12V	DC 12V	DC 9V~36V
Operating Temperature	-35°C~+70°C (ex WiFi)	-40°C~+70°C (ex WiFi)	-35°C~+70°C	-40°C~+80°C	-40°C~+85°C	-40°C~+80°C	-40°C~+75°C

Embedded PC	All in One Panel
	
FCU3001	FDU070K02 & FDU101K02
178×110×55mm	130×85mm
-	-
Jetson Xavier NX	Allwinner T507
Carmel ARM v8.2	ARM Cortex-A53
6	4
1.4GHz	1.5GHz
16GB	2GB
16GB	8GB
384 Volta Core+ 48 Tensor Cores	G31 MP2
21 TOPS	-
-	Linux4.9
ForlinxDesktop18.04	-
-	Android10.0
HDMI (4K)	LVDS (1280×800) HDMI (1920×1080)
4G / 5G	4G
4×10M/100M/1000Mbps	1×10M/100M/1000Mbps
2.4GHz & 5GHz	6221A-SRC
1	1
-	3
1	1
2×USB 2.0	2×USB 2.0
2	-
2	-
TF, SSD	TF
DC 12V	DC 12/24V
-25°C~+80°C	-

	LCD Module				
Image					
Model	FIT-LCD4.3	FIT-LCD7.0MIPI	FIT-LCD7.0	FIT-LCD7.0	FIT_LVDS10.1C_V2.0
Size	4.3"	7.0"	7.0"	7.0"	10.1"
Resolution	480*272	1024*600	800*480	1024*600 800*480	1028*800
Connector	FPC	FPC	FPC	FPC	LVDS
TP	Resistive	Capacitive	Resistive	Capacitive	Capacitive
Touch Interface	4-wire Resistive	IIC	4-wire Resistive	IIC	IIC

	Camera			Connector	Heat Sink
Image					
Model	OV5640	OV5645	OV13850	Surface Mount Connector ^(male)	SoM Heat Sink
Function	5.0MP	5.0MP	13.0MP	Connects SoM and Carrier Board	Cooling
Interface	DVP MIPI	MIPI	MIPI	/	/

	Expanding Modules& Accessories				
Image					
Model	5G Module	4G Module	WiFi&Bluetooth	FIT-GPS&BD-UM220 V1.0	FIT-USB-100M
Function	5G	4G	WiFi&Bluetooth	Based on NMEA0183, expandable to be compatible with Beidou	USB to 100Mbps
Interface	M.2	Mini PCIe	USB2.0/PCIe2.0	Serial	USB
Image					
Model	FIT-CAN-II_2515	FIT-485 v1.2	FIT-RS232-II v1.1	FIT-USB-TO-4-UARTS	MIPI TO HDMI/LVDS
Function	SPI to CAN	TTL to RS485	TTL to 232	USB to quad serial port	MIPI to HDMI/LVDS
Interface	SPI	Serial	Serial	USB	MIPI

Forlinx Embedded Technology Co., Ltd.



18 years'
History

200K+
Engineer Users

30K+
Enterprise Users

1M+Units
Annual Production Capability

Forlinx Embedded is a well-established and constantly growing company that focuses on designing, developing, and manufacturing embedded products. Since 2006, Forlinx has been committed to providing advanced embedded solutions including System on Module, SBC, and industrial embedded PCs. Forlinx keeps strategic partnerships with NXP, Allwinner, Rockchip, TI and other world-leading semiconductor companies and launches a series of ARM-based products qualified with CE, FCC, and RoHS certificates, which are widely used in industrial automation, transportation, medical, energy management, commercial electronics, etc. Forlinx's SoM annual production capability is more than 1 million pieces.

 Optimized OS

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 Robust Quality


 10+ Years Product Longevity


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